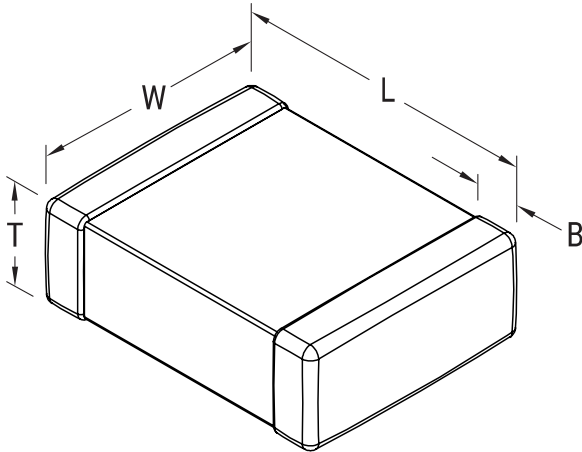


CBR06C859BAGAC

CBR-SMD RF COG, Ceramic, 8.5 pF, +/-0.1 pF, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603 / 1608



Click [here](#) for the 3D model.

General Information

Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
Typical Component Weight	5.29 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

Dimensions

L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
T	0.8mm +/-0.07mm
B	0.4mm +/-0.15mm
Case Code (EIA / mm)	0603 / 1608

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Specifications

Capacitance	8.5 pF
Tolerance	+/-0.1 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.175%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	570

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